

# QT-Brightek Chip LED Series

## SMD 1206 LED

Part No.: QBLP650-S2

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## Introduction

**Feature:**

- Water clear lens
- Package in tape and reel
- Bright 1206 LED package
- GaAsP technology

**Description:**

This top mount bright 1206 LEDs have a height profile of 1.1mm, which is ideal in any kind of back lighting application. Also, it is a light weight model that is good for miniature products.

**Application:**

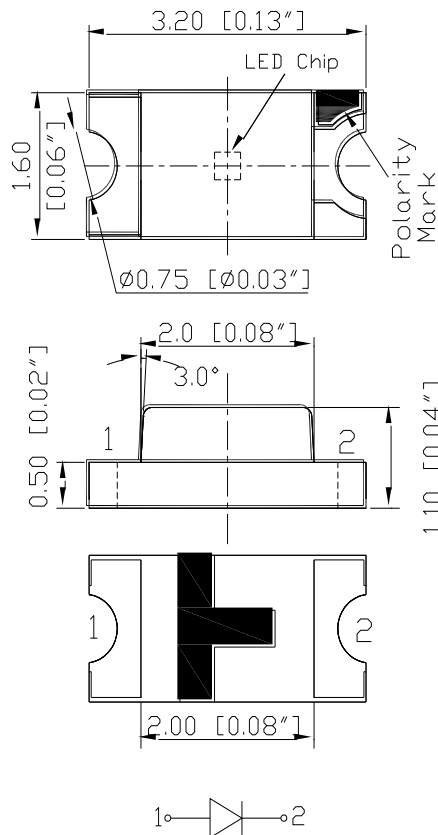
- Automotive dashboard lighting and button lighting
- Telecommunication and storage Back lighting
- Flat panel display back lighting

**Certification & Compliance:**

- TS16949
- ISO9001
- RoHS Compliant



**Dimension:**



Units: mm / tolerance = +/-0.1mm

**Electrical / Optical Characteristic (Ta=25 °C)**

Product	Color	I <sub>F</sub> (mA)	V <sub>F</sub> (V)		λ <sub>D</sub> (nm)			I <sub>V</sub> (mcd)	
			Typ.	Max.	Min.	Typ.	Max	Min.	Typ.
QBLP650-S2	Red	20	2.0	2.5	615	620	630	3.2	6.0

**Absolute Maximum Rating**

Material	P <sub>d</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)*	V <sub>R</sub> (V)	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)	T <sub>SO L</sub> (°C)**
GaAsP	75	30	125	5	-40 ~ +80	-40 ~ +85	260

\*Duty 1/8 @ 1kHz

\*\*IR Reflow for no more than 10 sec @ 260 °C

**Forward Voltage V<sub>F</sub> @ I<sub>F</sub>=20mA**

Bin	Min.	Max.	Unit
□	1.7	2.5	V

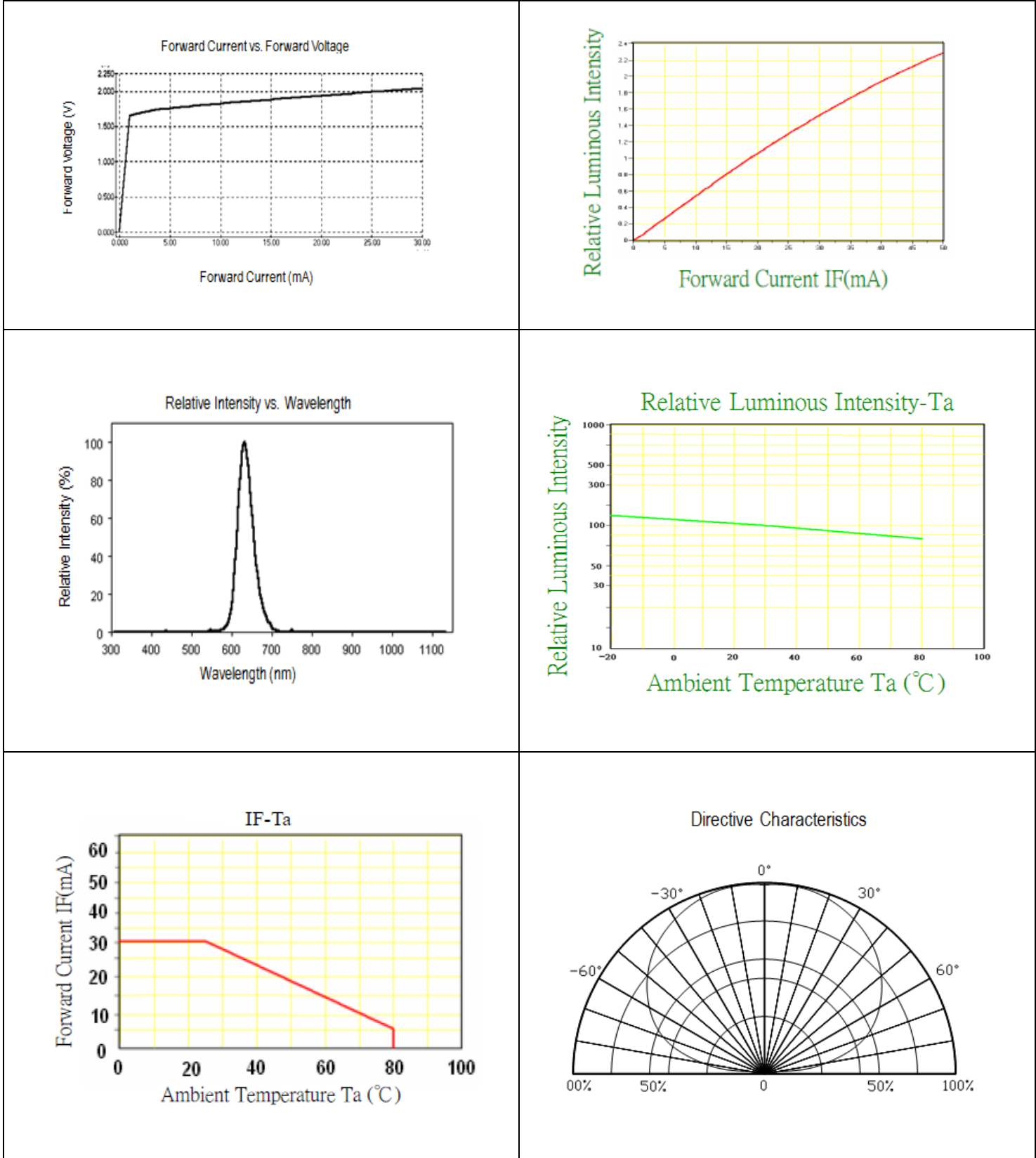
**Luminous Intensity I<sub>V</sub> @ I<sub>F</sub>=20mA**

Bin	Min.	Max.	Unit
7	3.2	5.0	mcd
8	5.0	8.0	
9	8.0	12.5	
A	12.5	16	

**Dominant Wavelength λ<sub>D</sub> @ I<sub>F</sub>=20mA**

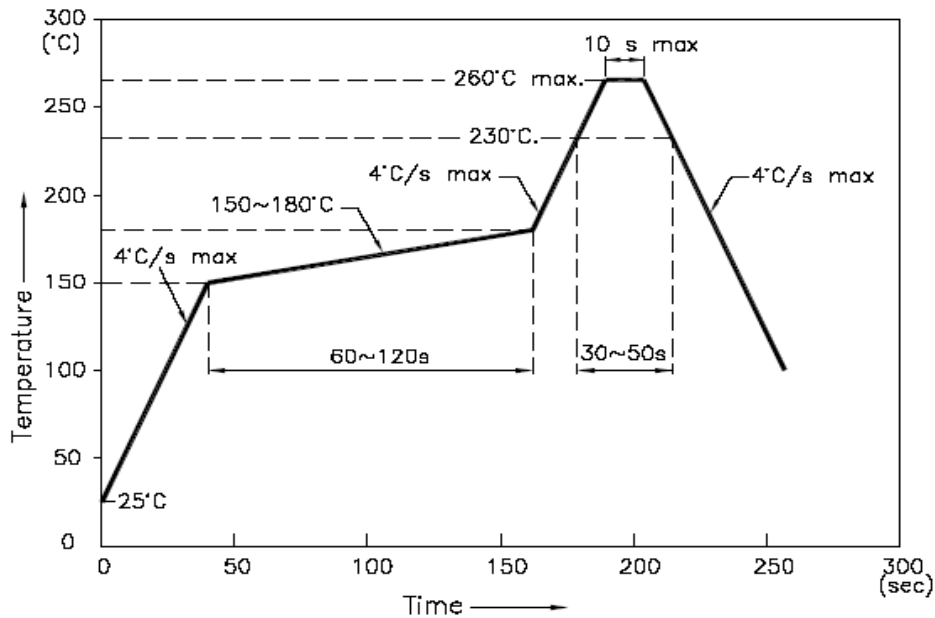
Bin	Min.	Max.	Unit
s	615	620	nm
t	620	625	
u	625	630	

**Characteristic Curves**

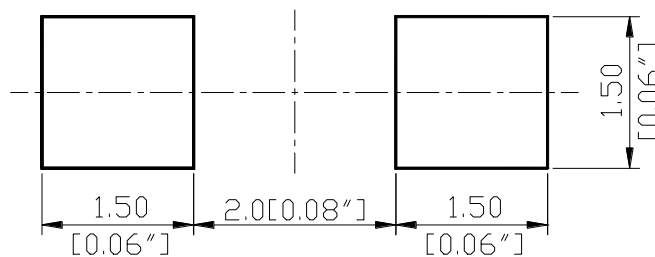


## Solder Profile & Footprint

- Recommended tin solder specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



### Recommended Pad Layout

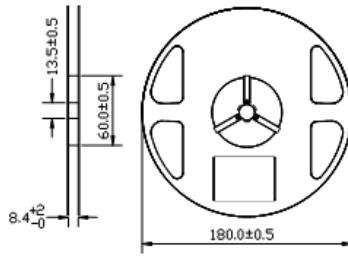


Units: mm

Tolerance: ± 0.1mm

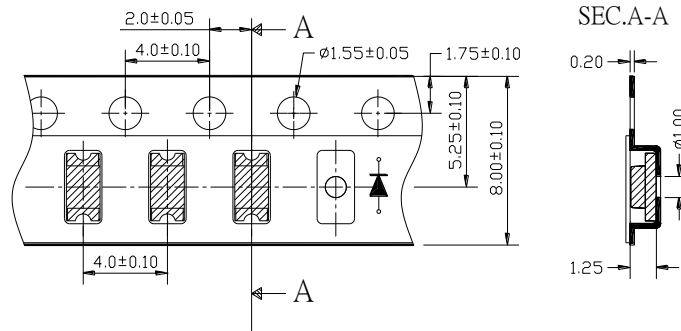
## Packing

### Reel Dimension:



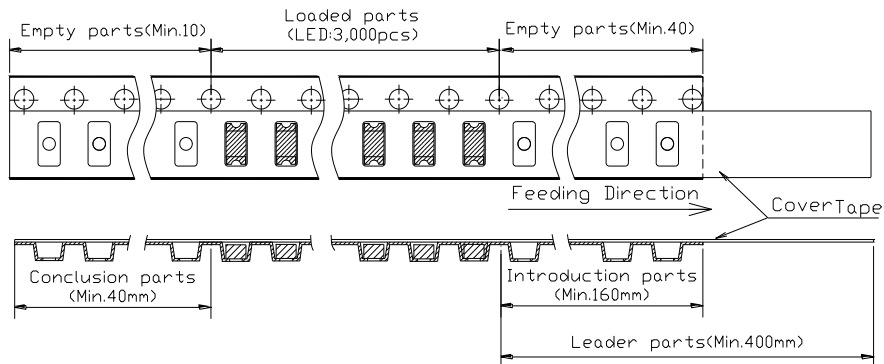
Unit: mm

### Tape Dimension:

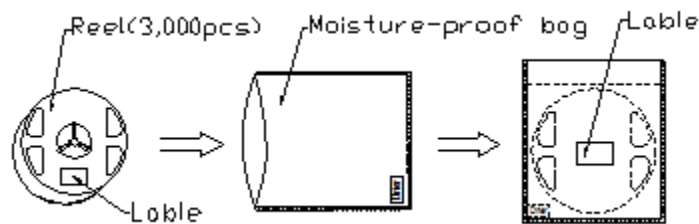


Unit: mm

### Arrangement of Tape:



### Packaging Specifications:



**Labeling**

Part No: \_\_\_\_\_

Customer P/N: \_\_\_\_\_

Item: \_\_\_\_\_

Q'ty: \_\_\_\_\_

Vf: \_\_\_\_\_

Iv: \_\_\_\_\_

WI: \_\_\_\_\_

Date: \_\_\_\_\_

**Made in China****Ordering Information**

Part #	Orderable Part #	Spec Range	Quantity per reel
QBLP650-S2	QBLP650-S2	Iv=13mcd typ. @ I <sub>F</sub> =20mA, λ <sub>D</sub> =630nm to 650nm	3,000 units



## Revision History

Description:	Revision #	Revision Date
New Release of QBLP650-S2	V1.0	09/18/2014

## Disclaimer

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.